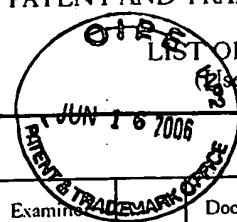


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Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
CME	AA 3,706,094	12/1972	COLE ET AL	342	44	
CME	AB 3,750,167	07/1973	GEHMAN ET AL.	342	44	
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CME	AN	CASSON, K. et al., "High Temperature Packaging: Flip Chip on Flexible Laminate", <u>Surface Mount Technology</u> , pp. 19-20 (1/1992)
CME	AO	JOHNSON, R.W., "Polymer Thick Films: Technology and Materials", <u>Circuits Manufacturing</u> (reprint), 4 pages (7/1982)
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EXAMINER

C. J. J. J.

DATE CONSIDERED

7/13/06

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